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# **Navitas**

# Let's go GaNFast™

# **GaNFast™ Power IC Modeling**

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- Introduction
- Spectre models for IC Design
- SPICE models for detailed system simulation
- SIMPLIS models for high level system simulation
- System simulation example: Active Clamp Flyback
- Conclusions





## Introduction

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# **Navitas eMode Power FET Technology**



- Large RQ FOM advantage
  - High frequency, high power density
- Lateral
  - Convenient voltage isolation
  - Multi device and IC integration
- Standard CMOS production
  - High yield, high capacity, multilevel metallization
  - Ideal for power IC development



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# **650 V Monolithic GaN Integration**



World's First GaN Power ICs



- Complicated power IC development requires capable process and IC design environment
  - PDK (Process Design Kit) is essential to reliability and manufacturability of IC products
  - Process corners, mismatch, temperature effect, layout parasitic, and design verification
- Accurate device modeling is essential part of PDK
  - Multi tiered models are developed for accurate and fast system simulation

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## **Power IC Spectre Models: IC Development**

- Excellent process design kit:
  - Device symbols
  - Pcells for automated device construction
  - Scalable, accurate
  - Verified for schematic and layout rules
  - Layout parasitic extraction
- Angelov, ASM and silicon models are not suitable
  - Lack of dMode, scalability, flexibility, speed
- Navitas GaN eMode FET scalable VerilogA model
  - Flexible: customized features/equations
  - High correlation between simulation and product
  - High-speed simulations

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# **Accurate over Temperature**



## • GaN FET I<sub>D</sub>V<sub>G</sub> Model with Temperature Effects

• Solid lines = measured, dotted lines = Cadence simulation



## **Accurate over Drain Voltage**



- Solid lines = measured, dotted lines = Cadence Spectre
- 20V rated eMode FET





## 650V rated eMode FET



ID_data_Vg=0V_model	ID_data_Vg=0.5V_model	•	ID_data_Vg=1V_model	•	ID_data_Vg=1.5V_model	•	ID_data_Vg=2V_model
ID_data_Vg=2.5V_model	<ul> <li>ID_data_Vg=3V_model</li> </ul>	٠	ID_data_Vg=3.5V_model	•	ID_data_Vg=4V_model	٠	ID_data_Vg=4.5V_model
<ul> <li>ID_data_Vg=5V_model</li> </ul>	• ID_data_Vg=5.5V_model	•	ID_data_Vg=6V_model	•	ID_data_Vg=6.5V_model	•	ID_data_Vg=7V_model
	ID_mod_Vg=0.5V_data		- ID_mod_Vg=1V_data		D_mod_Vg=1.5V_data		D_mod_Vg=2V_data
ID_mod_Vg=2.5V_data	ID_mod_Vg=3V_data	_	D_mod_Vg=3.5V_data		ID_mod_Vg=4V_data		D_mod_Vg=4.5V_data
	ID_mod_Vg=5.5V_data	_	D_mod_Vg=6V_data		D_mod_Vg=6.5V_data		=ID_mod_Vg=7V_data

# Bi-directional Drain Current vs. V<sub>D</sub>, V<sub>G</sub> GaNFast<sup>m</sup>

## 650V device model simulation with self-heating effects in Spectre



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# **Spice Models: Application Simulation**

#### Half Bridge Functional Blocks



#### **Top-Level Model Parameters**

#	Parameter Name	Description	Value	Unit
1	V <sub>CCTH</sub>	V <sub>cc</sub> Undervoltage Lockout Threshold	9.0	V
2	V <sub>CCHYS</sub>	V <sub>cc</sub> Undervoltage Lockout Hysteresis	0.5	V
3	V <sub>LTH</sub>	V <sub>L</sub> Input Logic Threshold	2.5	V
4	$V_{LHYS}$	V <sub>L</sub> Input Logic Hysteresis	0.5	V
5	V <sub>BTH</sub>	V <sub>B</sub> Undervoltage Lockout Threshold	9.0	V
6	V <sub>BHYS</sub>	V <sub>B</sub> Undervoltage Lockout Hysteresis	0.5	V

- Each Navitas power IC product will be released to public with a Spice model
  - It captures all functionalities and behaviors
- Spice models combines Angelov and behavioral techniques
  - Fast and accurate
  - Ideal for detailed in-circuit waveform and power loss study

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# 650V GaN eMode FET Output Curves



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# **Reverse Conduction Characteristics**





- Third quadrant I-V curves at 25C and 150C under gate bias
- Synchronous drive reduces reverse conduction loss

# **Output Capacitance and Charge Simulation GaNFast**

### Capacitance

## **Output Charge**



• Model matches the measurement in datasheet





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# Simplis Models: Ultra Fast System Sim GaNFast

#### Optimized for system simulation run time



# **Piece-wise Linear Model**

Simulation



Measured



• Nonlinear parameters are largely preserved: speed without loss of accuracy

# **Simplified Gate Driver**

- Gate driver replaced by "Level 1" SIMPLIS native
  - high-level gate driver block
- Driver parameters adjusted to meet timing of  $T_r$ ,  $T_f$

🖌 Edit Multi-Leve	el MOSFET Driver: U2	n
Model level Cevel 0 Cevel 1 Cevel 2	Multi-Level MOSFET Driver (Version 8.0+)         Parameters         Input parameters         Input parameters         Threshold       2         Image: Solution of the stress of the	U1-U1-D 67 R1 VCC D VVC D VVC D VVD D ZZ S V2 + V4 - VDD-CAP V2 + C1 BZX79-6V2 C2 10n D1 100p
		Low-side test circuit





# **Simulated Switching Waveforms**



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# **Active Clamp Flyback & GaN IC: High Density ZVS**











Up to 3x faster charging with half the size and weight for unparalleled mobility.





- World's smallest 27W USB-C
- Available now from **amazon**.com



- World's smallest Charger 42W (30W-C + 18W-A) + Battery Pack (5,000 mAhr)
- Available now from **CAPPIe Store**

# **ACF Simplis Models: Controller & GaN ICs**



Schematic from Texas Instruments. System jointly developed with Navitas

## **Simplis Sim Example: ACF Steady State**



- Detailed and accurate enough for system optimization
- V<sub>sw</sub> is half-bridge midpoint
  - Detailed soft switching waveforms
- I<sub>SEC</sub> SR current
  - Rms current analysis and reduction
- I<sub>PRI</sub> transformer current
  - Minimize negative current to achieve ZVS and reduce rms



# **Simplis Sim Example: Start-up**





- Various modes of operation can be observed and analyzed during startup
  - Current limit mode, burst mode, ACF mode, Vout transient

# **Simplis Sim Example: Load Transient**

- I<sub>o</sub> steps from full load to half load
- V<sub>OUT</sub> rises due to response delay
- Settles down by entering into burst mode



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# Conclusions



- eMode GaN is suitable for power IC integration
- Proprietary PDK for robust GaN Power IC design and manufacture
- Accurate multi-tier models are developed
- Advanced, highly-accurate, 4-terminal symmetric, scalable GaN FET Verilog model for IC design
- Accurate SPICE model for each product is essential for optimal accuracy
- SIMplis models also available for released products for ultra fast top level system design
- GaNFast<sup>™</sup> Power ICs are successfully developed and in mass production





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